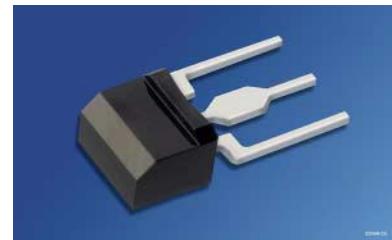


**Doppel-NPN-Silizium-Fototransistor mit Tageslichtsperrfilter
Dual Silicon NPN Phototransistor with Daylight-Cutoff Filter
Lead (Pb) Free Product - RoHS Compliant**

SFH 3162 F



Nicht für Neuentwicklung / Not for new design

Wesentliche Merkmale

- Tageslichtsperrfilter
- Doppel-Fototransistor nebeneinander positioniert
- Doppel-Fototransistor mit gemeinsamem Kollektor
- Optimale Kombination mit SFH4113 (horizontaler Enkoder)

Features

- Daylight Filter
- Dual Phototransistor positioned side by side
- Dual Phototransistor with common Collector
- Ideal combination with SFH4113 (horizontal encoder)

Anwendungen

- Richtungserkennung
- Empfänger in Lichtschranken
- Bandende-Erkennung (z.B. Videorecorder)
- Positionsüberwachung
- Barcode-Leser
- „Messen/Steuern/Regeln“
- Münzzähler

Applications

- Direction detection
- Detector in photointerrupters
- Tape end detection
- Position sensing
- Barcode reader
- For control and drive circuits
- Coin counters

Typ Type	Bestellnummer Ordering Code	$I_{ce(on)}$ [μA] ($V_{ce}=3.5V$, 950nm, $E_e=0.34mW/cm^2$)
SFH 3162 F	Q62702P5297	185 ... 585

Grenzwerte**Maximum Ratings**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebs- und Lagertemperatur Operating and storage temperature range	$T_{op}; T_{stg}$	- 40 ... + 85	°C
Löttemperatur bei Tauchlötzung Lötstelle \geq 2 mm vom Gehäuse, Lötzeit $t \leq 5$ s Dip soldering temperature \geq 2 mm distance from case bottom, soldering time $t \leq 5$ s	T_s	260	°C
Löttemperatur bei Kolbenlötzung Lötstelle \geq 2 mm vom Gehäuse, Lötzeit $t \leq 3$ s Iron soldering temperature \geq 2 mm distance from case bottom, soldering time $t \leq 3$ s	T_s	300	°C
Kollektor-Emitterspannung Collector-emitter voltage	V_{CE}	30	V
Kollektorstrom Collector current	I_C	10	mA
Kollektorspitzenstrom, $t < 10 \mu\text{s}$ Collector surge current	I_{CS}	20	mA
Emitter-Kollektorspannung Emitter-collector voltage	V_{EC}	7	V
Verlustleistung, $T_A = 25$ °C Total power dissipation	P_{tot}	100	mW
Wärmewiderstand Sperrsicht - Umgebung Thermal resistance junction - ambient	R_{thJA}	450	K/W

Kennwerte ($T_A = 25^\circ\text{C}$, $\lambda = 950 \text{ nm}$)**Characteristics**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Wellenlänge der max. Fotoempfindlichkeit Wavelength of max. sensitivity	$\lambda_{S \max}$	920	nm
Spektraler Bereich der Fotoempfindlichkeit $S = 10\%$ von S_{\max} Spectral range of sensitivity $S = 10\%$ of S_{\max}	λ	780 ... 1100	nm
Abmessungen der Chip-Fläche Dimension of chip area	$L \times B$ $L \times W$	1.23×0.66	mm \times mm
Bestrahlungsempfindliche Fläche Radiant sensitive area	A	2×0.15	mm 2
Halbwinkel Half angle	ϕ	± 75	Grad deg.
Kapazität Capacitance $V_{CE} = 3V, f = 1 \text{ MHz}, E = 0$	C_{CE}	3.2	pF
Dunkelstrom Dark current $V_{CE} = 10 \text{ V}$	I_{CEO}	0.1 (≤ 100)	nA
Fotostrom Photocurrent $E_e = 0.34 \text{ mW/cm}^2, V_{CE} = 3.5 \text{ V}$	$I_{e(on)}^{1)}$	185 585	μA
Temperaturkoeffizient von $I_{e(on)}$ Temperature coefficient of $I_{e(on)}$ $V_{ce} = 5 \text{ V}$	TC	+ 0.9	%/K

1) $I_{e(on)}$ ist der Mittelwert der Emitterströme der beiden Phototransistoren. $I_{e(on)}$ is the mean value of the emitter currents of the two phototransistors.

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Emitterstrom-Verhältnis der 2 Fototransistoren Emitter current ratio of the 2 phototransistors $V_{eco} = 3.5V, E_e = 0.34mW/cm^2$	$R^1)$	1 ... 1.1	
Übersprechen zwischen T1 und T2 Crosstalk between T1 and T2 $E_e = 0.34 \text{ mW/cm}^2, \lambda = 950\text{nm}, V_{CE} = 3.5 \text{ V}$	$(Ie1 - Ie1')/Ie1^2)$	3	%
Anstiegszeit/Abfallzeit Rise and fall time $I_C = 1 \text{ mA}, V_{CC} = 5 \text{ V}, R_L = 1 \text{ k}\Omega$	t_r t_f	11 11	μs
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage $I_C = 50\mu\text{A},$ $E_e = 0.5 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	V_{CESat}	0.1 (≤ 0.4)	V

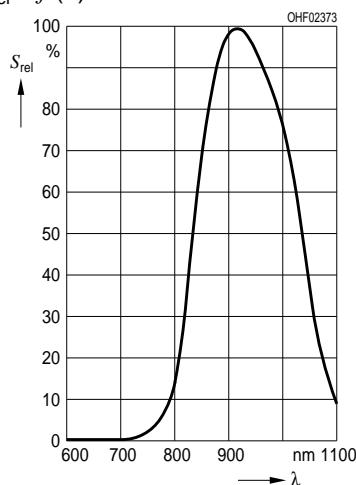
¹⁾ $Ie(\text{max})/Ie(\text{min})$

²⁾ Testing condition

- a) $Ie1$ measured while the emitter of T2 is grounded
- b) $Ie1'$ is the $Ie1$ reading while the emitter of T2 is not connected

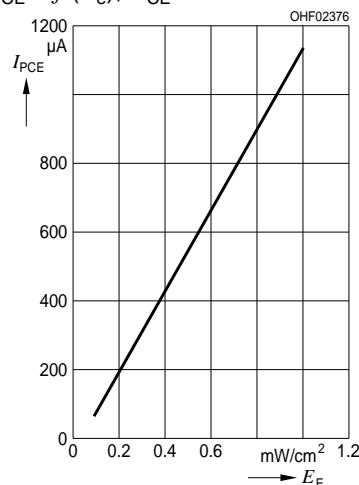
Relative Spectral Sensitivity

$$S_{\text{rel}} = f(\lambda)$$



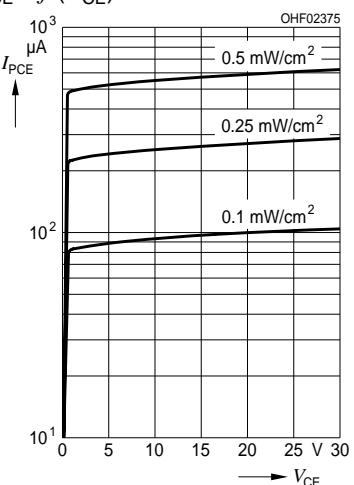
Photocurrent

$$I_{\text{PCE}} = f(E_e), V_{\text{CE}} = 5 \text{ V}$$



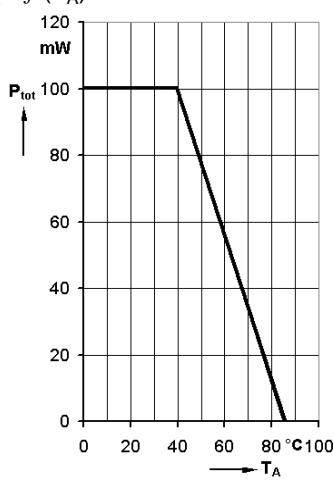
Photocurrent

$$I_{\text{PCE}} = f(V_{\text{CE}})$$



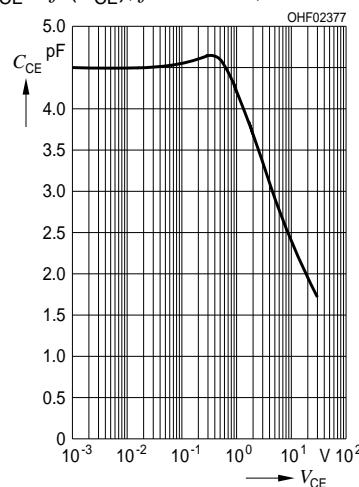
Total Power Dissipation

$$P_{\text{tot}} = f(T_A)$$

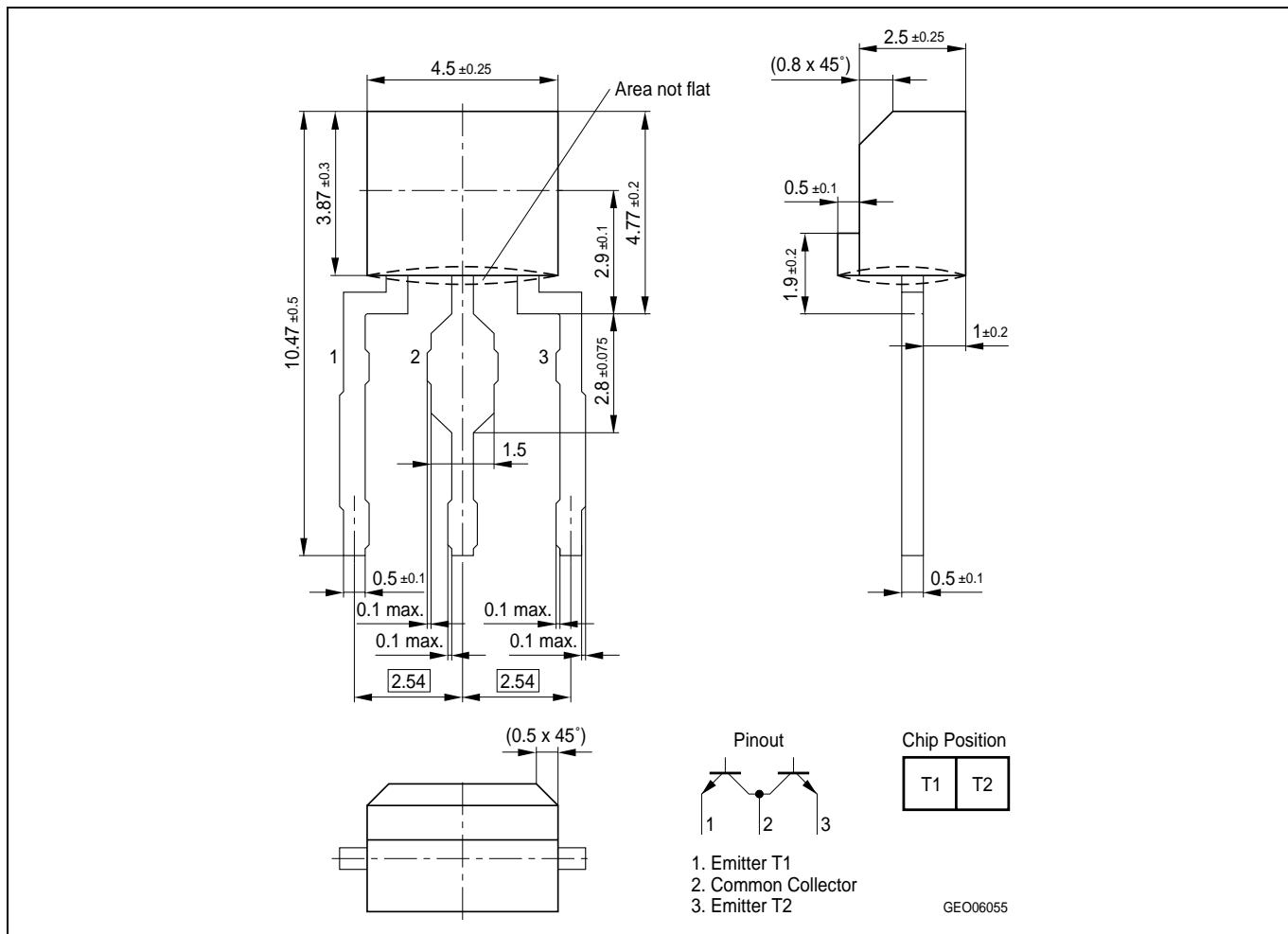


Collector-Emitter Capacitance

$$C_{\text{CE}} = f(V_{\text{CE}}), f = 1 \text{ MHz}, E = 0$$



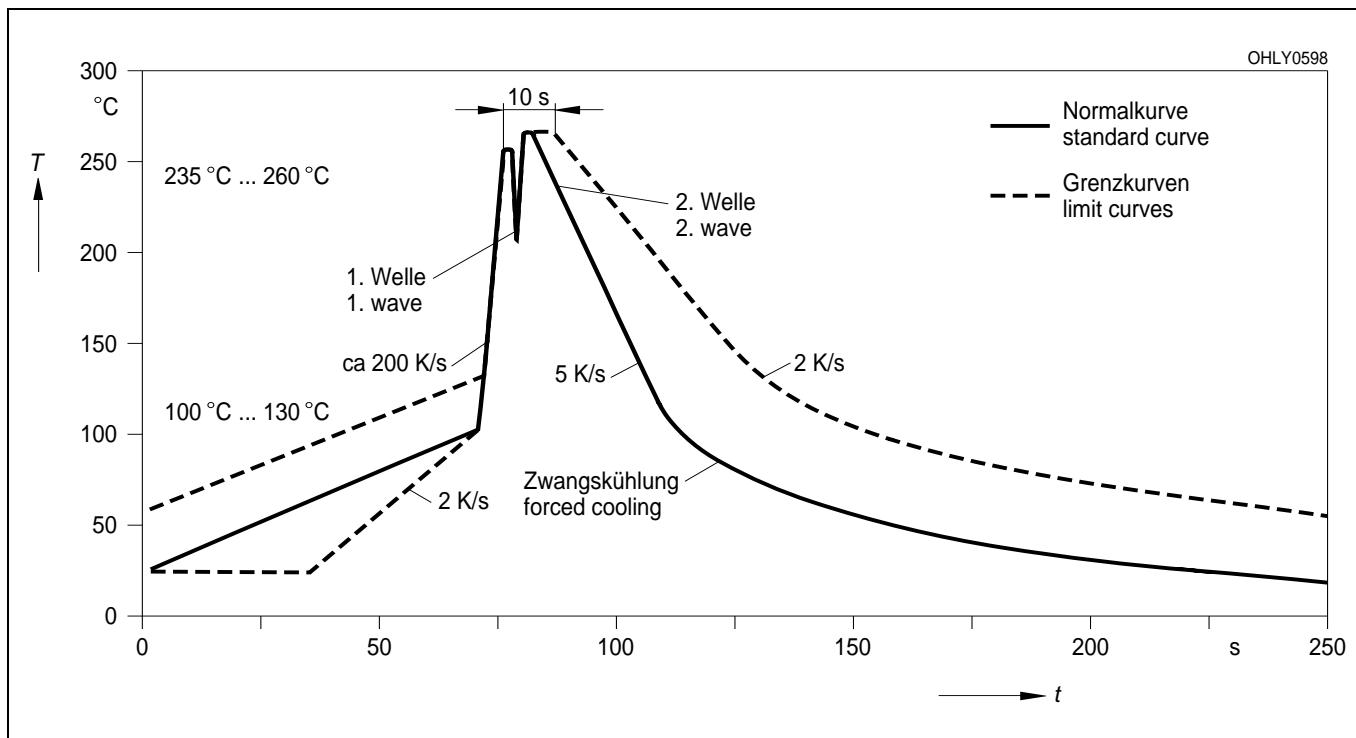
Maßzeichnung
Package Outlines



Maße in mm (inch) / Dimensions in mm (inch).

Lötbedingungen
Soldering Conditions
Wellenlöten (TTW)
TTW Soldering

(nach CECC 00802)
 (acc. to CECC 00802)



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